



Features

- 310 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 5 V
- Bidirectional Configuration
- AEC-Q101 Qualified



IEC Compatibility (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 17A (8/20 μs)

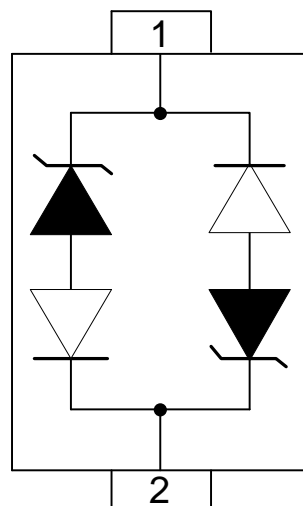
Mechanical Characteristics

- JEDEC SOD-323 package
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant

Applications

- Ethernet - 10/100/1000 Base T
- Cellular Phones
- Handheld - Wireless Systems
- Personal Digital Assistant (PDA)
- USB Interface

Schematic & PIN Configuration

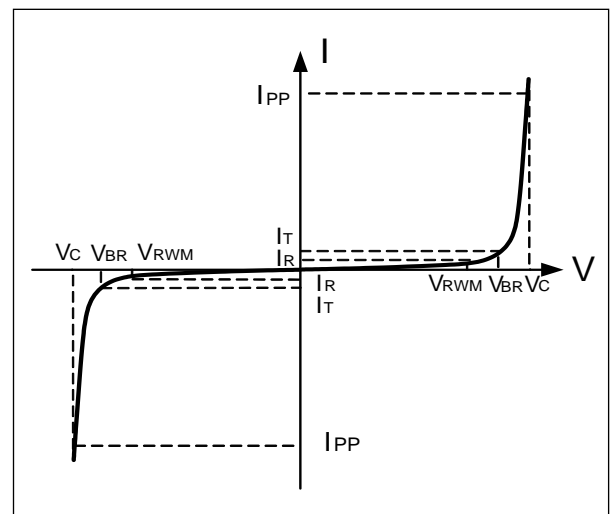


BIDIRECTIONAL

Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	310	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	17	A
Operating Temperature	T_J	-55 to +125	$^{\circ}C$
Storage Temperature	T_{STG}	-55 to +150	$^{\circ}C$

Electrical Parameters ($T=25^{\circ}C$)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Electrical Characteristics

DW05DLC-B-AT-S						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	6		9	V
Reverse Leakage Current	I_R	$V_{RWM}=5V, T=25^{\circ}C$			500	nA
Clamping Voltage	V_C	$I_{PP}=17A, t_p=8/20\mu s$		15.5	18.3	V
Dynamic Resistance ^{1,2}	R_{DYN}	$TLP=0.2/100ns$		0.3		Ω
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A$ $t_p = 0.2/100ns$		9.5		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A$ $t_p = 0.2/100ns$		13.2		V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		1.0	1.35	pF

Note: 1、TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

2、Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit"

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Typical Characteristics

Figure 1: Peak Pulse Power Vs Pulse Time

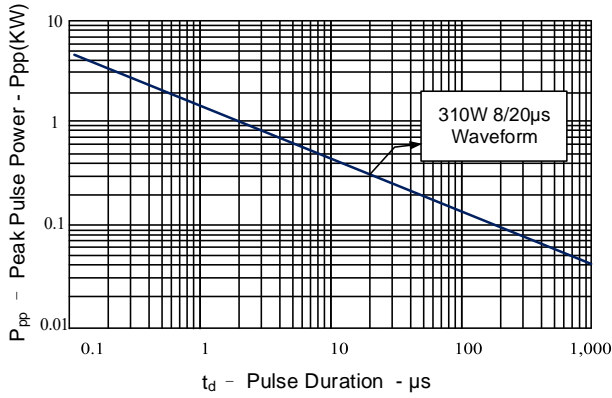


Figure 2: Power Derating Curve

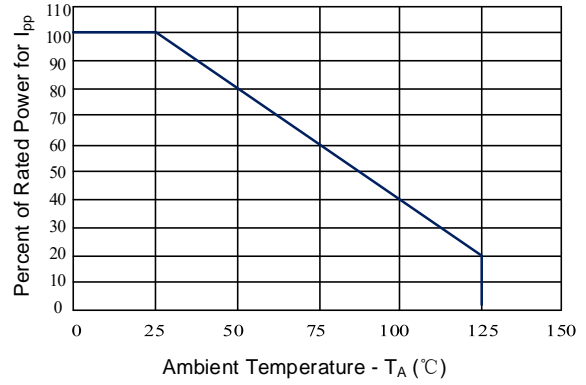


Figure 3: Clamping Voltage vs. Peak Pulse Current

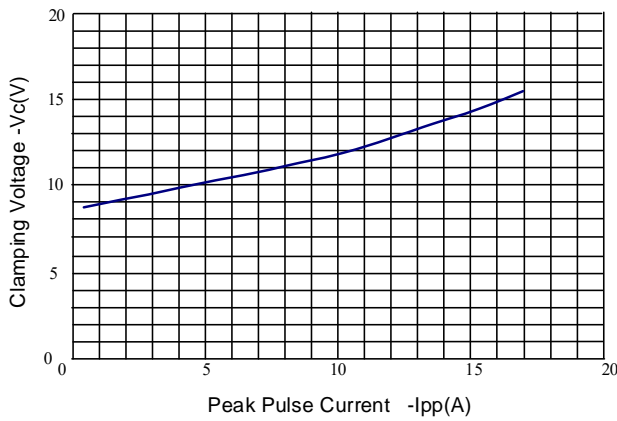


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

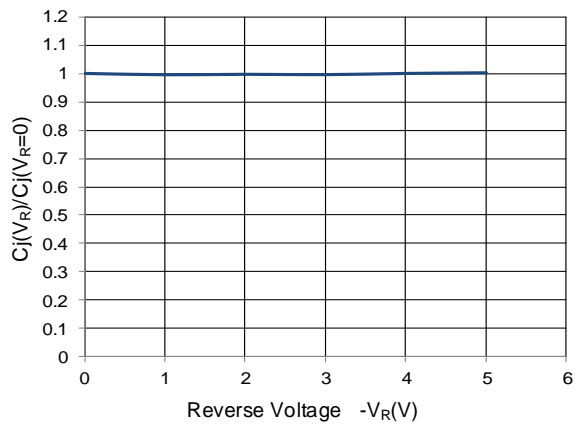


Figure 5: TLP Positive I-V Curve

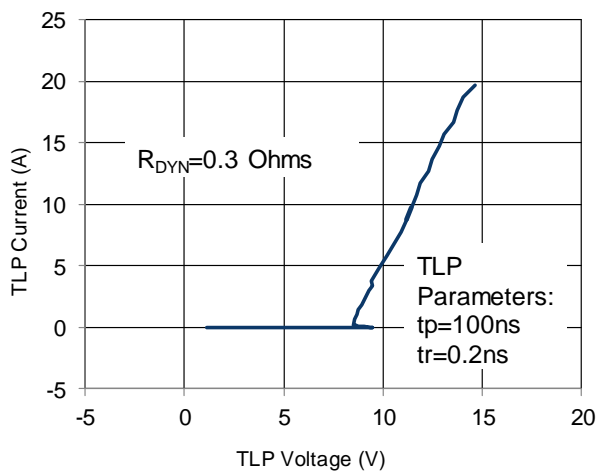
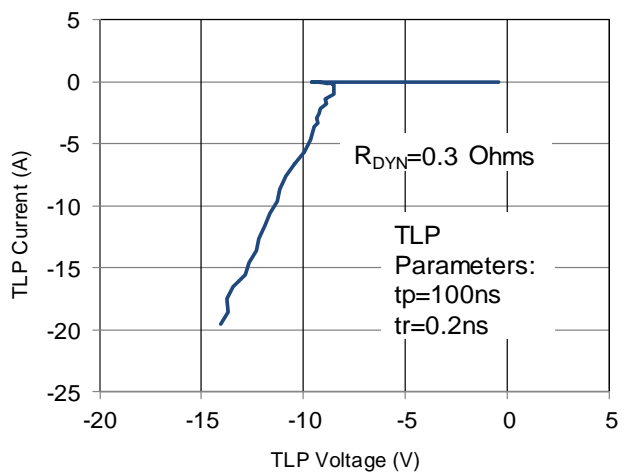


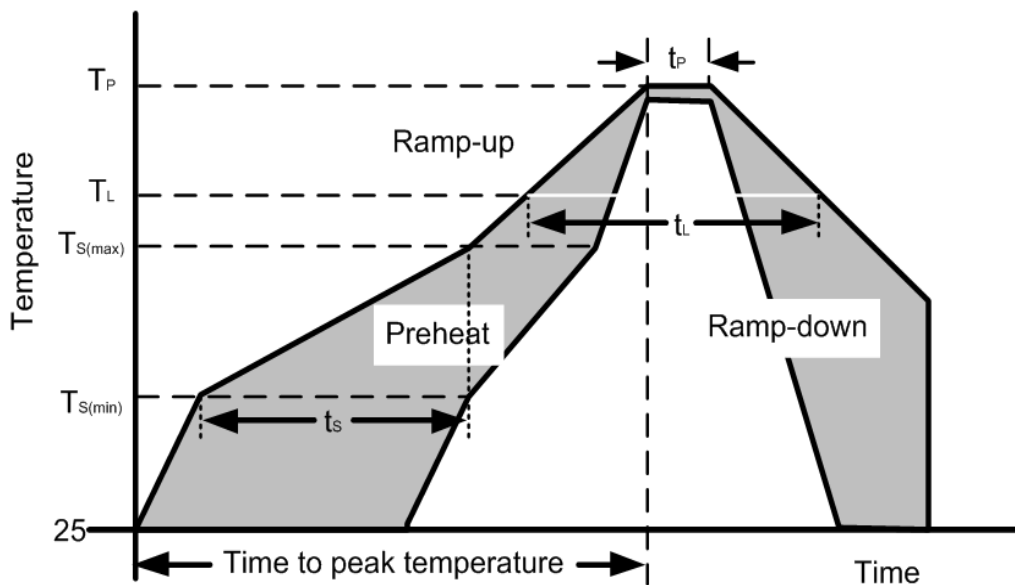
Figure 6: TLP Negative I-V Curve



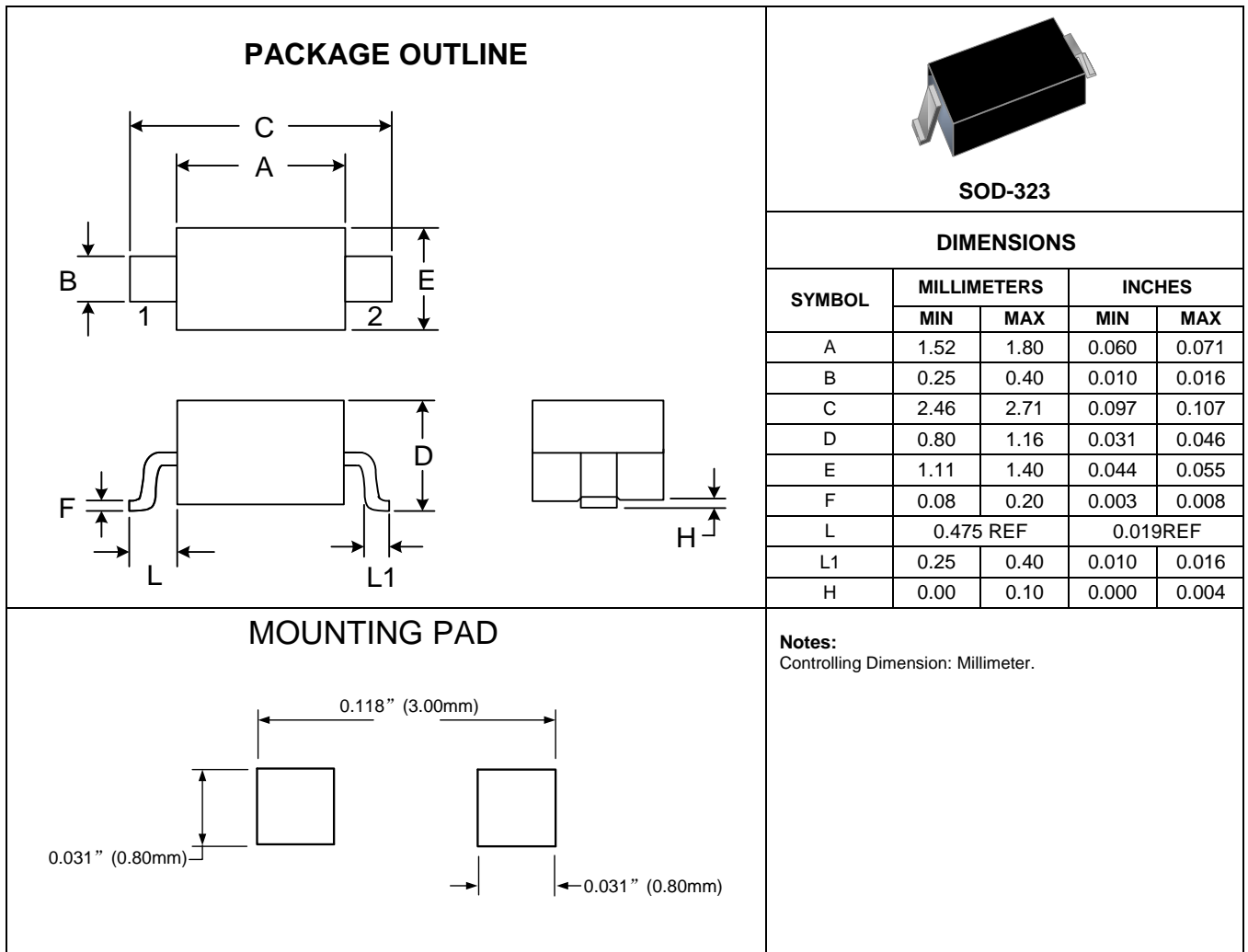


Soldering Parameters


Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing – SOD-323



Marking Codes

Part Number	DW05DLC-B-AT-S
Marking Code	

Package Information

Qty: 3k/Reel